

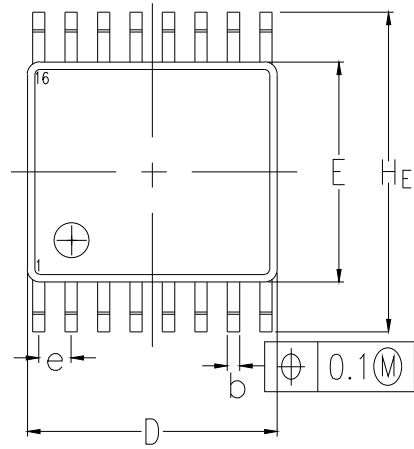
BASED ON JEDEC JEP95: MO-153

1. DIMENSIONS

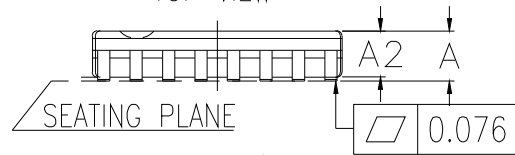
DIMENSIONS IN MILLIMETERS

DATE CREATED	REV	REVISIONS	
		DESCRIPTION	AUTHOR
9/20/18	00	Revised from PSC-4749 PGG16	Eddie Lee/CM
6/14/19	01	Correct Title Description	RC/CM
8/29/19	02	EPAD OPTION ADDED	CM

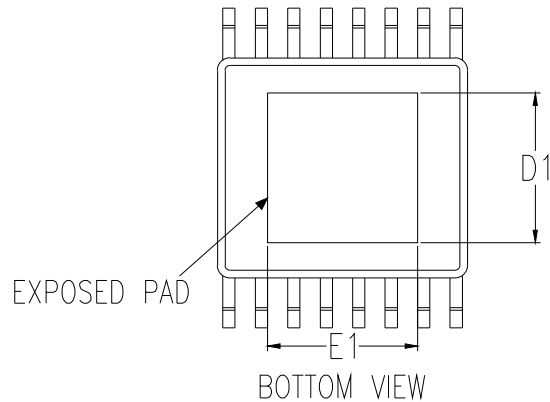
NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE



TOP VIEW

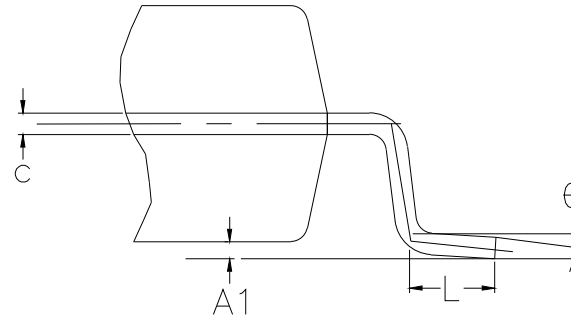


SIDE VIEW



BOTTOM VIEW

VIEW X



DIMENSIONS	min	max
A	0.90	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.20	0.30
c	0.10	0.20
D	4.90	5.10
E	4.30	4.50
D1	REFER TO EPAD OPTION	
E1	REFER TO EPAD OPTION	
e	0.65nom	
HE	6.20	6.60
L	0.45	0.75
θ	0°	8°

* WITHOUT MOLD FLASH

EPAD OPTIONS:

SYMBOL	P1			P2		
	MIN	NOM	MAX	MIN	NOM	MAX
D1	-	3.00	-	2.50	2.70	2.90
E1	-	3.00	-	2.50	2.70	2.90

- 2. WEIGHT ≤ 0.05 g
- 3. BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu-ALLOY
- 5. LEAD FINISH SOLDER PLATING
- 6. LEAD FORM Z-BENDS

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR XXX± ± XXXX±			6024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572
	www.IDT.com		
TITLE ENG16 Package Outline Drawing 5.0 x 4.4 mm Body, 0.65mm Pitch TSSOP with EPAD			
SIZE C	DRAWING No. PSC-4761	REV 02	
DO NOT SCALE DRAWING			SHEET 1 OF 2

